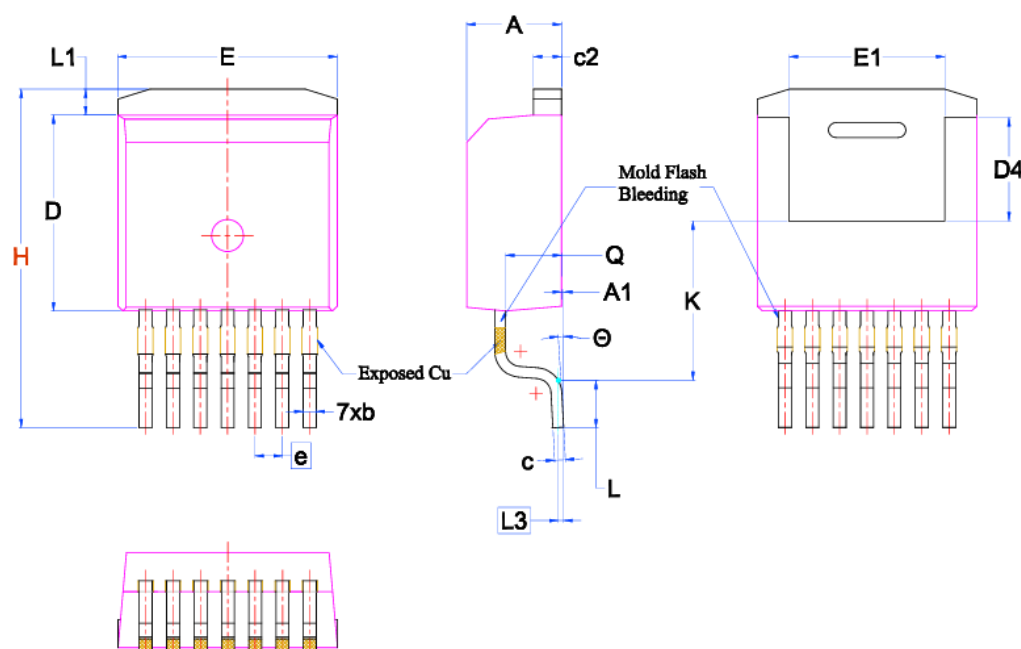




Package Dimensions

Product	SiC MOSFET	Package	TO-263-7
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SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.30	4.40	4.50
A1	0.00	0.10	0.20
b	0.50	0.60	0.70
c	0.45	0.50	0.60
c2	1.20	1.30	1.40
D	8.93	9.08	9.23
D4	4.65	4.80	4.95
E	10.08	10.18	10.28
E1	6.82	7.22	7.62
e	1.27 BSC		
H	15.00	15.70	16.00
K	7.30		
L	1.90	2.20	2.60
L1	1.00	1.20	1.40
L3	0.25 BSC		
Q	2.45	2.60	2.75
Θ	0°	3°	7°

Note:

1. All Dimensions Are In mm.
2. Dimension D & E Do Not Include Mold Flash.
Mold Flash Shall Not Exceed 0.254mm Pre Side.
These Dimensions Are Measured At The Outermost Extreme Of The Plastic Body.
3. Thermal Pad Contour Optional Within Dimensions E, L1, D4 & E1.
4. Dimension D4 & E1 Establish A Minmum Mounting Surface for The Thermal Pad.
5. "*" is reference .
6.  is Exposed Cu.